Product End-of-Life Disassembly Instructions

Product Category: Personal Computers

Marketing Name / Model
[List multiple models if applicable.]

HP ProDesk 485 G1 Microtower Business PC

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>2</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td></td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td>5</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>Power cord</td>
<td>1</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td></td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

PSG instructions for this template are available at [EL-MF877-01](EL-MF877-01)
Components, parts and materials containing refractory ceramic fibers
Components, parts and materials containing radioactive substances

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Screw driver</td>
<td>T-15</td>
</tr>
<tr>
<td>Micro shear</td>
<td>YN-3</td>
</tr>
<tr>
<td>Screw driver</td>
<td>PH1</td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove access panel. (see Figure 1-3)
2. Remove front bezel. (see Figure 4)
3. Disconnect cooler cable then remove the cooler from board. (see Figure 5-7)
4. Disconnect 24 pin power cable ◦ SATA cable ◦ SATA power cable ◦ CPU power cable. (see Figure 8-11)
5. Remove the ODD and HDD from chassis (see Figure 12-16)
6. Disconnect the MCR cable from board then remove the MCR. (see Figure 17-19)
7. Disconnect system fan cable then remove the system fan from chassis (see Figure 20-22)
8. Disconnect FIO cables and open the cable clip. (see Figure 23-24)
9. Remove the FIO module from chassis. (see Figure 25-26)
10. Disconnect PWR cable then remove it from chassis. (see Figure 27-28)
11. Disconnect speaker cable then remove it from chassis. (see Figure 29-31)
12. Remove the Memory from chassis. (see Figure 32)
13. Remove the battery from the board. (see Figure 33)
14. Remove Mother board from chassis. (see Figure 34-36)
15. Remove the I/O shielding from chassis. (see Figure 37)
16. Remove the PSU from chassis. (see Figure 38-39)
17. Remove the PSU chassis and remove the PSU board.. (see Figure 40-43)
18. Remove the Electrolytic Capacitors from PSU board. (see Figure 44-50)

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
Figure 1: Loose the two screws from access panel

Figure 2: Slide the access panel back

Figure 3: Rotate the top of the panel away to remove it

Figure 4: Pull the 3 hooks and rotate to remove the front bezel

PSG instructions for this template are available at EL-MF877-01
Figure 5 Disconnect the cooler cable from MB

Figure 6 Loose 4 screws from cooler and remove it

Figure 7 Remove the cooler from board

Figure 8 Disconnect the SATA cables from board

PSG instructions for this template are available at EL-MF877-01
PSG instructions for this template are available at [EL-MF877-01](#).
Figure 13: Remove the ODD from chassis

Figure 14: Disconnect the SATA and power cables from HDD

Figure 15: Loose the HDD screws

Figure 16: Remove the HDD from chassis

PSG instructions for this template are available at EL-MF877-01
Figure 17 Disconnect the MCR cable from MB

Figure 18 Loose the MCR screws

Figure 19 Remove the MCR from chassis

Figure 20 Disconnect system fan cable from board

PSG instructions for this template are available at [EL-MF877-01](EL-MF877-01)
PSG instructions for this template are available at [EL-MF877-01](EL-MF877-01)
Figure 25: Loosen the screw of the FIO cable

Figure 26: Remove the FIO cable from chassis

Figure 27: Disconnect PWR cable from MB

Figure 28: Remove the PWR cable

PSG instructions for this template are available at [EL-MF877-01](#)
Figure 29 Disconnect speaker cable from board

Figure 30 Loose the screw of speaker

Figure 31 Remove the speaker form chassis

Figure 32 Push the hooks on both sides and then pick up the memory

PSG instructions for this template are available at [EL-MF877-01](#)
Figure 33: Remove the battery from the MB

Figure 34: Loosen the 6 screws from MB

Figure 35: Loosen the 8 screws from MB and remove it

Figure 36: Remove MB from chassis

PSG instructions for this template are available at EL-MF877-01
Figure 37 Push the I/O shielding to the inside of the chassis and remove it.

Figure 38 Loose 4 screws of PSU and remove it.

Figure 39 Pull up the PSU and remove it.

Figure 40 Loose 4 screws from PSU cage and remove it.

PSG instructions for this template are available at EL-MF877-01
Figure 41: Cut the cable tie

Figure 42: Disconnect the fan cable from PSU

Figure 43: Loosen 4 screws from the PSU PCA and remove it

Figure 44: Heat the solder of Electrolytic Capacitors greater than 2.5 cm in diameter or height and remove it

PSG instructions for this template are available at EL-MF877-01
Figure 49: Heat the solder of Electrolytic Capacitors greater than 2.5cm in diameter or height and remove it (Gamay 300W E*6 PSU-Bestec)

Figure 50: Heat the solder of Electrolytic Capacitors greater than 2.5cm in diameter or height and remove it (Gamay 300W E*6 PSU-Acbel)

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